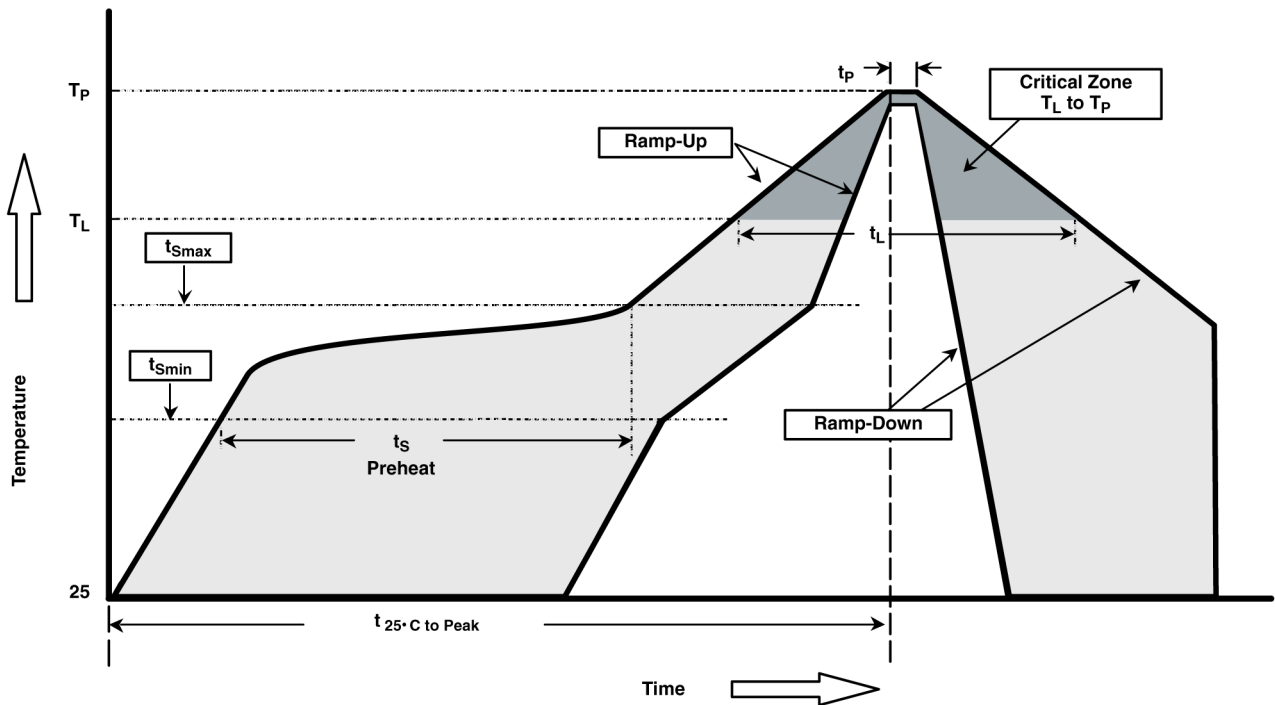


APPENDIX A

CLASSIFICATION REFLOW PROFILES (IPC/JEDEC J-STD-020C)			
Profile Feature	Sn-Pb Eutectic Assembly		Pb-Free Assembly
	Large Body	Small Body	All Packages
Reflow Conditions	Pkg. Thickness ≥ 2.5 mm or Pkg. Volume ≥ 350 mm ³	Pkg. Thickness < 2.5 mm and Pkg. Volume < 350 mm ³	See <i>Vishay Lead (Pb)-Free Family Summary Sheet—Active Components</i> (http://www.vishay.com/doc?49321) for exceptions.
Average ramp-up rate (T_L to T_P)	3 °C/second max.		3 °C/second max.
Preheat			
<ul style="list-style-type: none"> Temperature Min. (T_{Smin}) Temperature Max. (T_{Smax}) Time (min to max) (t_s) 	100 °C 150 °C 60-120 seconds		150 °C 200 °C 60-180 seconds
Time maintained above:			
<ul style="list-style-type: none"> Temperature (T_L) Time (t_L) 	183 °C 60-150 seconds		217 °C 60-150 seconds
Peak Temperature (T_P)	225 +0/-5 °C	240 +0/-5 °C	260 +0/-5 °C
Time within 5 °C of actual Peak Temperature (t_p)	10-30 seconds		20-40 seconds
Ramp-down Rate	6 °C/second max.		6 °C/second max.
Time 25 °C to Peak Temperature ($t_{25\text{ °C to Peak}}$)	6 minutes max.		8 minutes max.

NOTE: All temperatures refer to topside of the package, measured on the package body surface.



Definitions of Classification Reflow Profiles as Given in the above Table